General Description

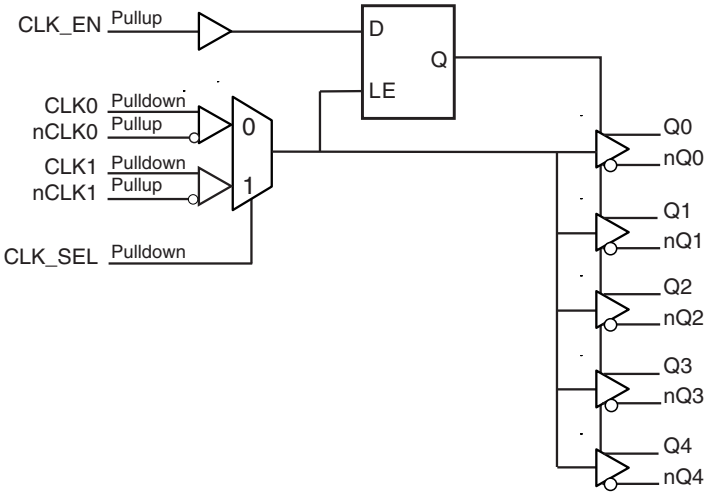
The ICS85304I-01 is a low skew, high performance 1-to-5 Differential-to-3.3V LVPECL fanout buffer. The ICS85304I-01 has two selectable clock inputs. The CLKx, nCLKx pairs can accept most standard differential input levels. The clock enable is internally synchronized to eliminate runt clock pulses on the outputs during asynchronous assertion/ deassertion of the clock enable pin.

Guaranteed output and part-to-part skew characteristics make the ICS85304I-01 ideal for those applications demanding well defined performance and repeatability.

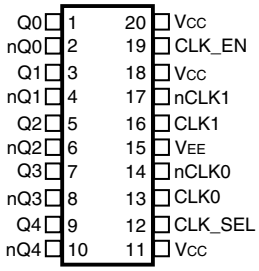
Features

- Five 3.3V differential LVPECL output pairs
- Selectable differential CLKx, nCLKx input pairs
- CLKx, nCLKx input pairs can accept the following differential levels: LVDS, LVPECL, LVHSTL and HCSL levels
- Maximum output frequency: 650MHz
- Translates any single-ended input signal to 3.3V LVPECL levels with resistor bias on nCLKx inputs
- Output skew: 60ps (maximum)
- Part-to-part skew: 300ps (maximum)
- Propagation delay: 2.1ns (maximum)
- Full 3.3V supply mode
- -40°C to 85°C ambient operating temperature
- Lead-free (RoHS 6) package

Block Diagram



Pin Assignment



ICS85304I-01

20-Lead TSSOP
6.5mm x 4.4mm x 0.925mm
package body
G Package
Top View

Pin Description and Pin Characteristics Tables

Table 1. Pin Descriptions

Number	Name	Type		Description
1, 2	Q0, nQ0	Output		Differential output pair. LVPECL interface levels.
3, 4	Q1, nQ1	Output		Differential output pair. LVPECL interface levels.
5, 6	Q2, nQ2	Output		Differential output pair. LVPECL interface levels.
7, 8	Q3, nQ3	Output		Differential output pair. LVPECL interface levels.
9, 10	Q4, nQ4	Output		Differential output pair. LVPECL interface levels.
11, 18, 20	V_{CC}	Power		Positive supply pins.
12	CLK_SEL	Input	Pulldown	Clock select input. When HIGH, selects CLK1, nCLK1 inputs. When LOW, selects CLK0, nCLK0 inputs. LVTTL/LVCMOS interface levels.
13	CLK0	Input	Pulldown	Non-inverting differential clock input.
14	nCLK0	Input	Pullup	Inverting differential clock input.
15	V_{EE}	Power		Negative supply pin.
16	CLK1	Input	Pulldown	Non-inverting differential clock input.
17	nCLK1	Input	Pullup	Inverting differential clock input.
19	CLK_EN	Input	Pullup	Synchronizing clock enable. When HIGH, clock outputs follow clock input. When LOW, Qx outputs are forced LOW, nQx outputs are forced HIGH. LVTTL/LVCMOS interface levels.

NOTE: *Pullup and Pulldown* refer to internal input resistors. See Table 2, *Pin Characteristics,* for typical values.

Table 2. Pin Characteristics

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
C_{IN}	Input Capacitance			4		pF
$R_{PULLDOWN}$	Input Pulldown Resistor			51		kΩ
R_{PULLUP}	Input Pullup Resistor			51		kΩ

Function Tables

Table 3A. Control Input Function Table

Inputs			Outputs	
CLK_EN	CLK_SEL	Selected Source	Q[0:4]	nQ[0:4]
0	0	CLK0, nCLK0	Disabled; LOW	Disabled; HIGH
0	1	CLK1, nCLK1	Disabled; LOW	Disabled; HIGH
1	0	CLK0, nCLK0	Enabled	Enabled
1	1	CLK1, nCLK1	Enabled	Enabled

After CLK_EN switches, the clock outputs are disabled or enabled following a rising and falling input clock edge as shown in Figure 1. In the active mode, the state of the outputs are a function of the CLKx, nCLKx inputs as described in Table 3B.

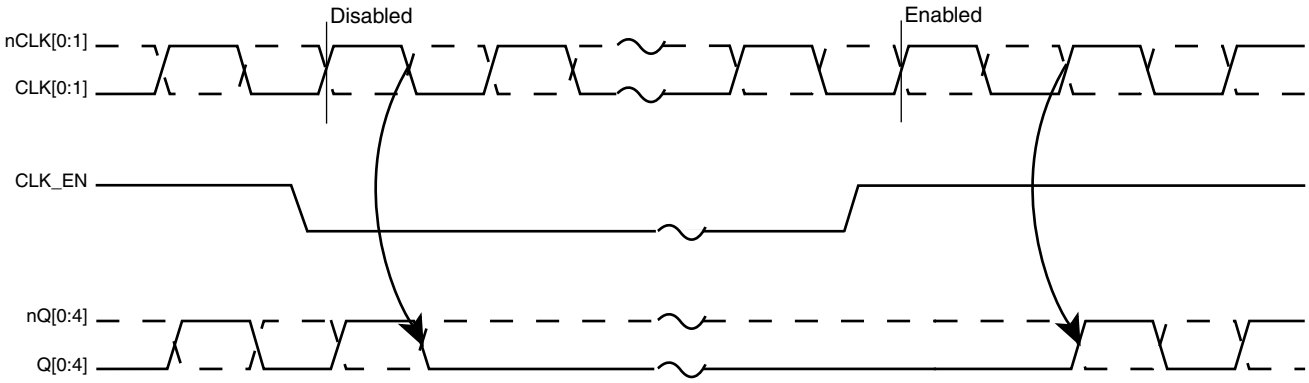


Figure 1. CLK_EN Timing Diagram

Table 3B. Clock Input Function Table

Inputs		Outputs		Input to Output Mode	Polarity
CLK0 or CLK1	nCLK0 or nCLK1	Q[0:4]	nQ[0:4]		
0	1	LOW	HIGH	Differential to Differential	Non-Inverting
1	0	HIGH	LOW	Differential to Differential	Non-Inverting
0	Biased; NOTE 1	LOW	HIGH	Single-Ended to Differential	Non-Inverting
1	Biased; NOTE 1	HIGH	LOW	Single-Ended to Differential	Non-Inverting
Biased; NOTE 1	0	HIGH	LOW	Single-Ended to Differential	Inverting
Biased; NOTE 1	1	LOW	HIGH	Single-Ended to Differential	Inverting

NOTE 1: Please refer to the Application Information section, *Wiring the Differential Input to Accept Single-Ended Levels.*

Absolute Maximum Ratings

NOTE: Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These ratings are stress specifications only. Functional operation of product at these conditions or any conditions beyond those listed in the *DC Characteristics or AC Characteristics* is not implied. Exposure to absolute maximum rating conditions for extended periods may affect product reliability.

Item	Rating
Supply Voltage, V_{CC}	4.6V
Inputs, V_I	-0.5V to V_{CC} + 0.5V
Outputs, I_O Continuous Current Surge Current	 50mA 100mA
Package Thermal Impedance, θ_{JA}	91.1°C/W (0 mps)
Storage Temperature, T_{STG}	-65°C to 150°C

DC Electrical Characteristics

Table 4A. Power Supply DC Characteristics, V_{CC} = 3.3V ± 5%, V_{EE} =0V, T_A = -40°C to 85°C

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
V_{CC}	Core Supply Voltage		3.135	3.3	3.465	V
I_{EE}	Power Supply Current				55	mA

Table 4B. LVCMOS/LVTTL DC Characteristics, V_{CC} = 3.3V ± 5%, V_{EE} = 0V, T_A = -40°C to 85°C

Symbol	Parameter		Test Conditions	Minimum	Typical	Maximum	Units
V_{IH}	Input High Voltage			2		V_{CC} + 0.3	V
V_{IL}	Input Low Voltage			-0.3		0.8	V
I_{IH}	Input High Current	CLK_EN	V_{CC} = V_{IN} = 3.465V			5	µA
		CLK_SEL	V_{CC} = V_{IN} = 3.465V			150	µA
I_{IL}	Input Low Current	CLK_EN	V_{CC} = 3.465V, V_{IN} = 0V	-150			µA
		CLK_SEL	V_{CC} = 3.465V, V_{IN} = 0V	-5			µA

Table 4C. Differential DC Characteristics, V_{CC} = 3.3V ± 5%, V_{EE} = 0V, T_A = -40°C to 85°C

Symbol	Parameter		Test Conditions	Minimum	Typical	Maximum	Units
I_{IH}	Input High Current	nCLK0, nCLK1	V_{CC} = V_{IN} = 3.465V			5	µA
		CLK0, CLK1	V_{CC} = V_{IN} = 3.465V			150	µA
I_{IL}	Input Low Current	nCLK0, nCLK1	V_{CC} = 3.465V, V_{IN} = 0V	-150			µA
		CLK0, CLK1	V_{CC} = 3.465V, V_{IN} = 0V	-5			µA
V_{PP}	Peak-to-Peak Voltage; NOTE 1			0.15		1.3	V
V_{CMR}	Common Mode Input Voltage; NOTE 1, 2			V_{EE} + 0.5		V_{CC} – 0.85	V

NOTE 1: V_{IL} should not be less than -0.3V
NOTE 2: Common mode input voltage is defined as V_{IH}.

Table 4D. LVPECL DC Characteristics, V_{CC} = 3.3V ± 5%, V_{EE} =0V, T_A = -40°C to 85°C

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
V_{OH}	Output High Current; NOTE 1		V_{CC} – 1.4		V_{CC} – 0.9	µA
V_{OL}	Output Low Current; NOTE 1		V_{CC} – 2.1		V_{CC} – 1.7	µA
V_{SWING}	Peak-to-Peak Output Voltage Swing		0.6		1.0	V

NOTE 1: Outputs terminated with 50Ω to V_{CC} – 2V.

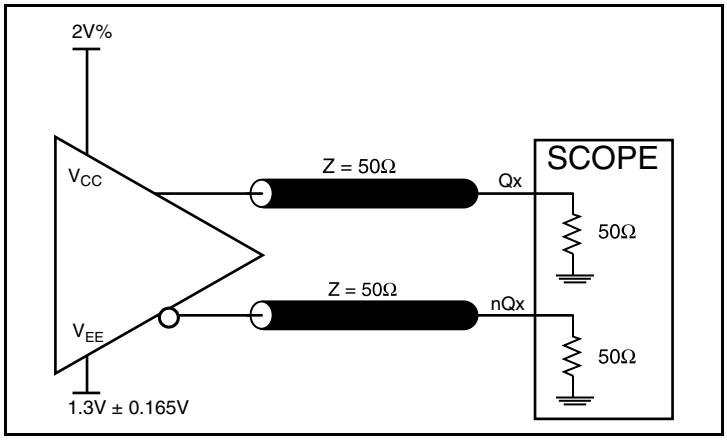
AC Electrical Characteristics

Table 5. AC Characteristics, V_{CC} = 3.3V ± 5%, V_{EE} =0V, T_A = -40°C to 85°C

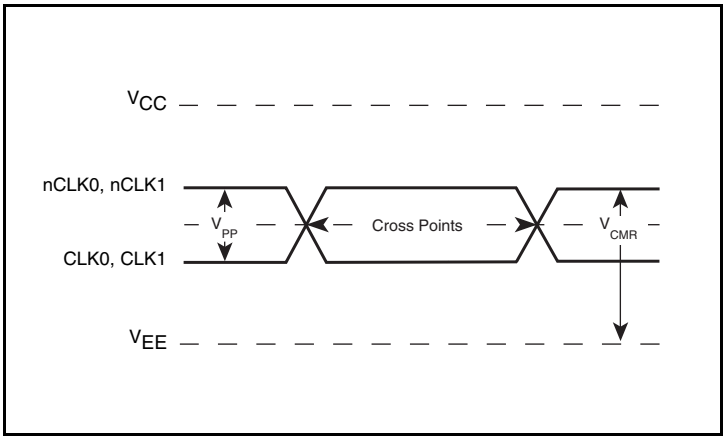
Parameter	Symbol	Test Conditions	Minimum	Typical	Maximum	Units
f_{OUT}	Maximum Output Frequency				650	MHz
t_{PD}	Propagation Delay; NOTE 1	$f \leq$ 650MHz	1.0		2.1	ns
*t*sk(o)	Output Skew; NOTE 2, 3				60	ps
*t*sk(pp)	Part-to-Part Skew; NOTE 3, 4				300	ps
t_R / t_F	Output Rise/Fall Time	20% to 80%	300		700	ps
odc	Output Duty Cycle		45		55	%

NOTE: The device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.
NOTE: All parameters measured at 500MHz unless noted otherwise
NOTE 1: Measured from the differential input crossing point to the differential output crosspoint.
NOTE 2: Defined as skew between outputs at the same supply voltage and with equal load conditions. Measured at the output differential crosspoint.
NOTE 3: This parameter is defined in accordance with JEDEC Standard 65.
NOTE 4: Defined as skew between outputs on different devices operating at the same supply voltage, same temperature, same frequency and with equal load conditions. Using the same type of inputs on each device, the outputs are measured at the differential crosspoint.

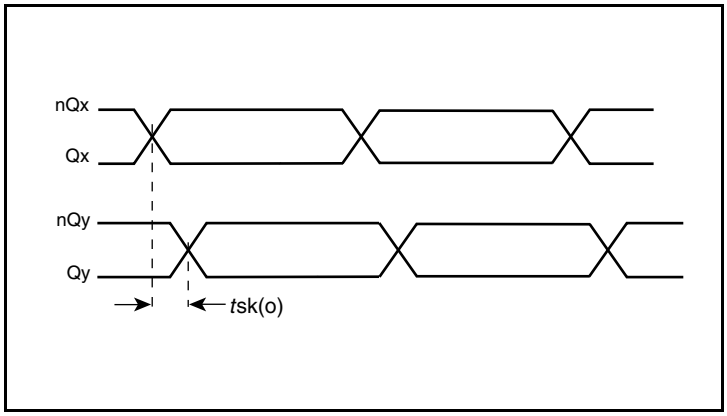
Parameter Measurement Information



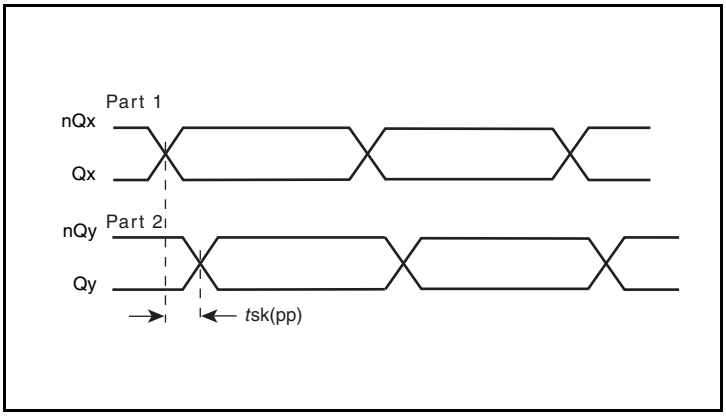
3.3V Output Load AC Test Circuit



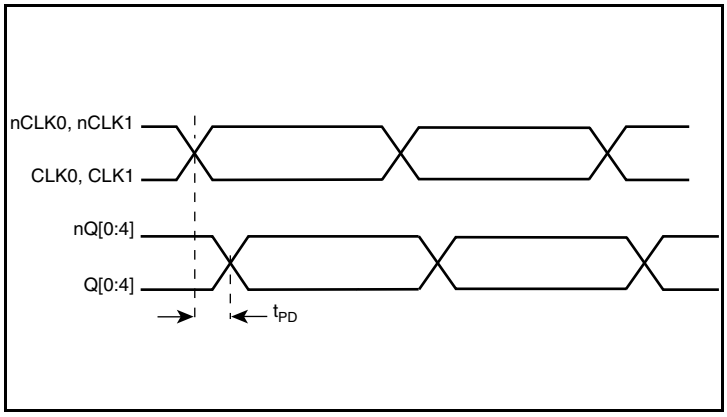
Differential Input Level



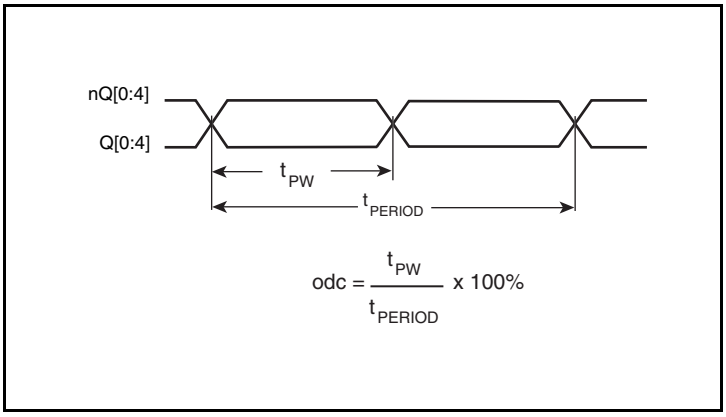
Output Skew



Part-to-Part Skew

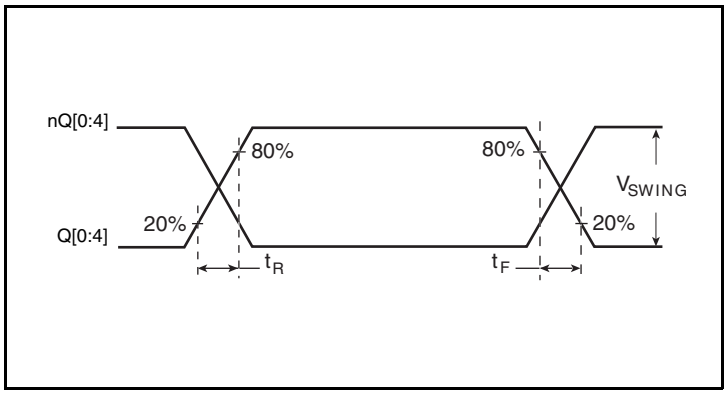


Propagation Delay



Output Duty Cycle/Pulse Width/Period

Parameter Measurement Information, continued



Output Rise/Fall Time

Applications Information

Wiring the Differential Input to Accept Single-Ended Levels

Figure 2 shows how a differential input can be wired to accept single ended levels. The reference voltage $V_1 = V_{CC}/2$ is generated by the bias resistors R1 and R2. The bypass capacitor (C1) is used to help filter noise on the DC bias. This bias circuit should be located as close to the input pin as possible. The ratio of R1 and R2 might need to be adjusted to position the V_1 in the center of the input voltage swing. For example, if the input clock swing is 2.5V and V_{CC} = 3.3V, R1 and R2 value should be adjusted to set V_1 at 1.25V. The values below are for when both the single ended swing and V_{CC} are at the same voltage. This configuration requires that the sum of the output impedance of the driver (Ro) and the series resistance (Rs) equals the transmission line impedance. In addition, matched termination at the input will attenuate the signal in half. This can be done in one of two ways. First, R3 and R4 in parallel should equal the transmission line impedance. For most 50Ω applications, R3 and R4 can be 100Ω. The values of the resistors can be increased to reduce the loading for slower and weaker LVCMOS driver. When using single-ended signaling, the noise rejection benefits of differential signaling are reduced. Even though the differential input can handle full rail LVCMOS signaling, it is recommended that the amplitude be reduced. The datasheet specifies a lower differential amplitude, however this only applies to differential signals. For single-ended applications, the swing can be larger, however V_{IL} cannot be less than -0.3V and V_{IH} cannot be more than V_{CC} + 0.3V. Though some of the recommended components might not be used, the pads should be placed in the layout. They can be utilized for debugging purposes. The datasheet specifications are characterized and guaranteed by using a differential signal.

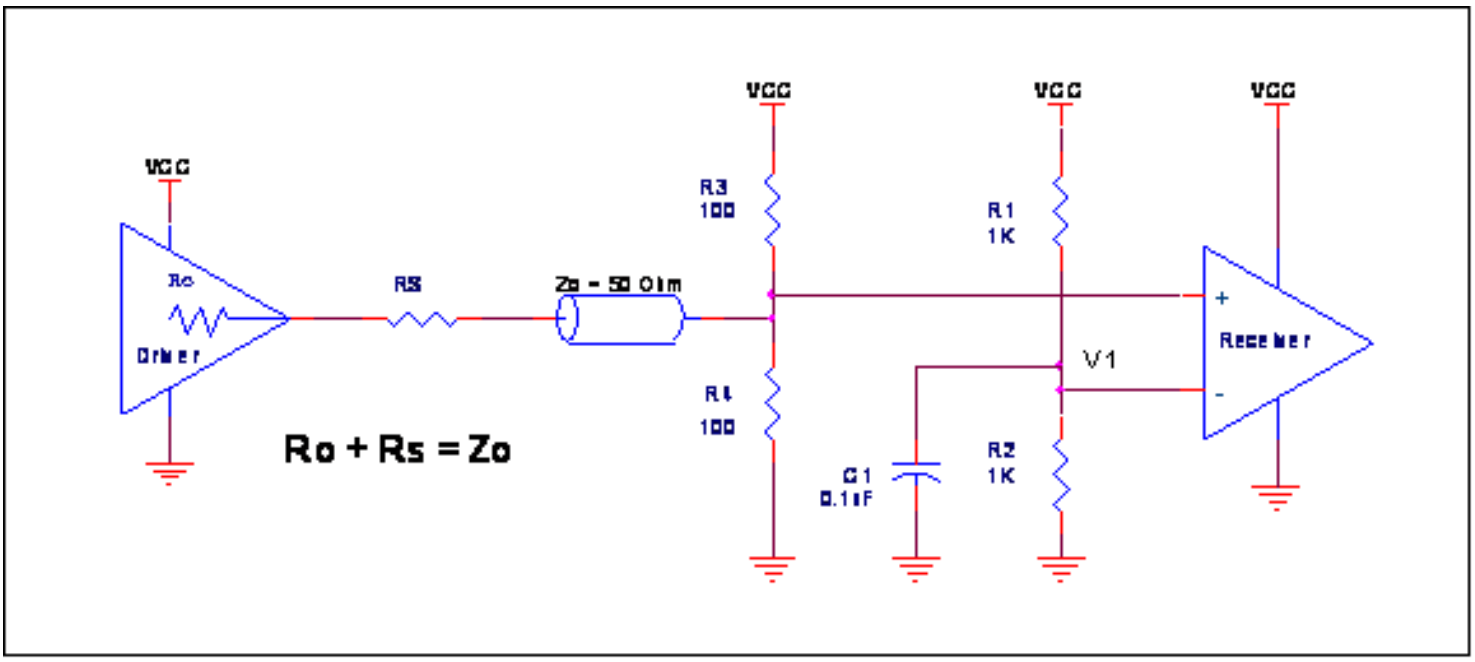


Figure 2. Recommended Schematic for Wiring a Differential Input to Accept Single-ended Levels

Differential Clock Input Interface

The CLK /nCLK accepts LVDS, LVPECL, LVHSTL, HCSL and other differential signals. Both V_{SWING} and V_{OH} must meet the V_{PP} and V_{CMR} input requirements. *Figures 3A to 3E* show interface examples for the CLK /nCLK input driven by the most common driver types. The input interfaces suggested here are examples only. Please consult with the vendor of the driver component to confirm the driver termination requirements. For example, in Figure 3A, the input termination applies for IDT open emitter LVHSTL drivers. If you are using an LVHSTL driver from another vendor, use their termination recommendation.

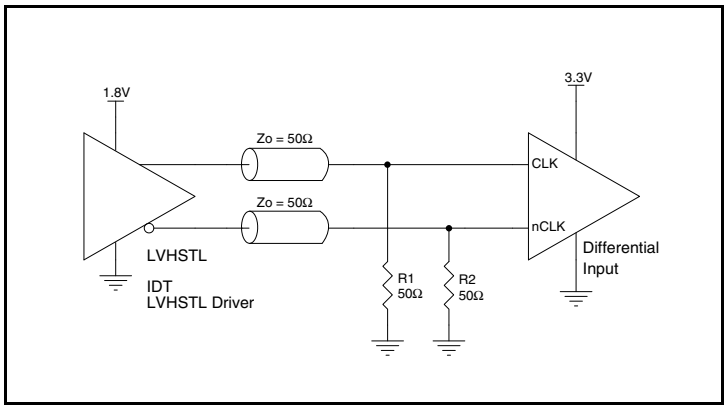


Figure 3A. CLK/nCLK Input Driven by an IDT Open Emitter LVHSTL Driver

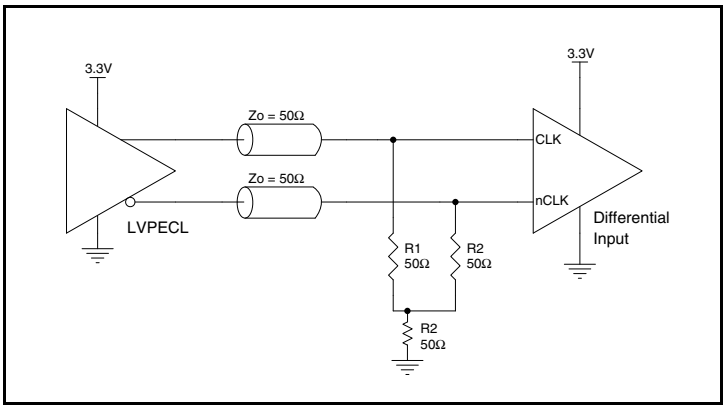


Figure 3B. CLK/nCLK Input Driven by a 3.3V LVPECL Driver

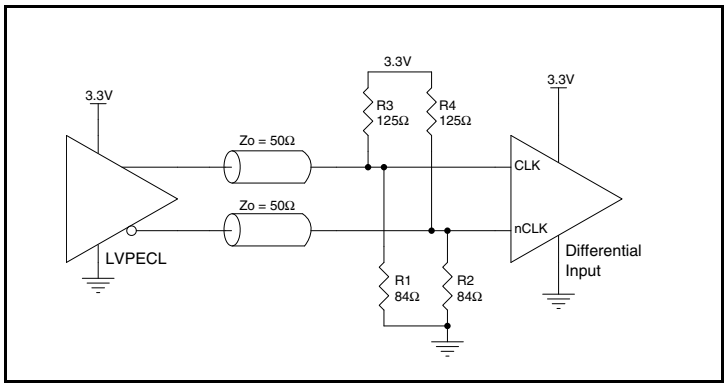


Figure 3C. CLK/nCLK Input Driven by a 3.3V LVPECL Driver

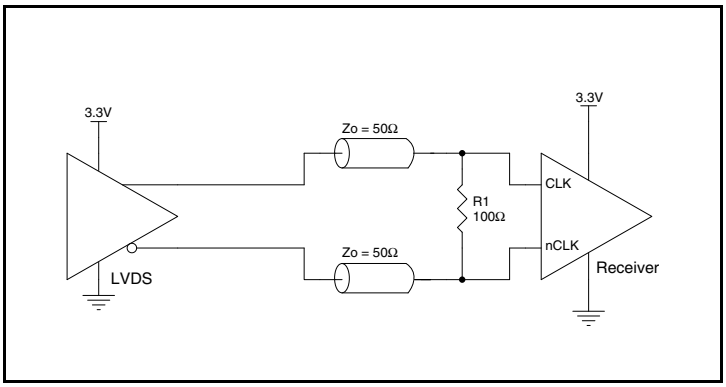


Figure 3D. CLK/nCLK Input Driven by a 3.3V LVDS Driver

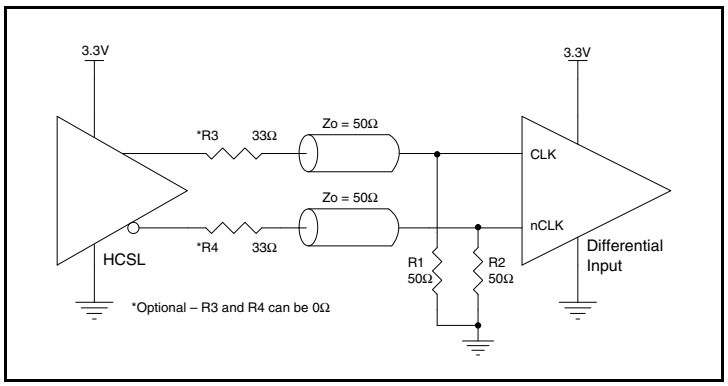


Figure 3E. CLK/nCLK Input Driven by a 3.3V HCSL Driver

Recommendations for Unused Input and Output Pins

Inputs:

LVCMOS Control Pins

All control pins have internal pullup or pulldown resistors; additional resistance is not required but can be added for additional protection. A 1kΩ resistor can be used.

CLK/nCLK Inputs

For applications not requiring the use of the differential input, both CLK and nCLK can be left floating. Though not required, but for additional protection, a 1kΩ resistor can be tied from CLK to ground.

Outputs:

LVPECL Outputs

All unused LVPECL output pairs can be left floating. We recommend that there is no trace attached. Both sides of the differential output pair should either be left floating or terminated.

Termination for 3.3V LVPECL Outputs

The clock layout topology shown below is a typical termination for LVPECL outputs. The two different layouts mentioned are recommended only as guidelines.

The differential outputs are low impedance follower outputs that generate ECL/LVPECL compatible outputs. Therefore, terminating resistors (DC current path to ground) or current sources must be used for functionality. These outputs are designed to drive 50Ω transmission lines. Matched impedance techniques should be used to maximize operating frequency and minimize signal distortion. *Figures 4A and 4B* show two different layouts which are recommended only as guidelines. Other suitable clock layouts may exist and it would be recommended that the board designers simulate to guarantee compatibility across all printed circuit and clock component process variations.

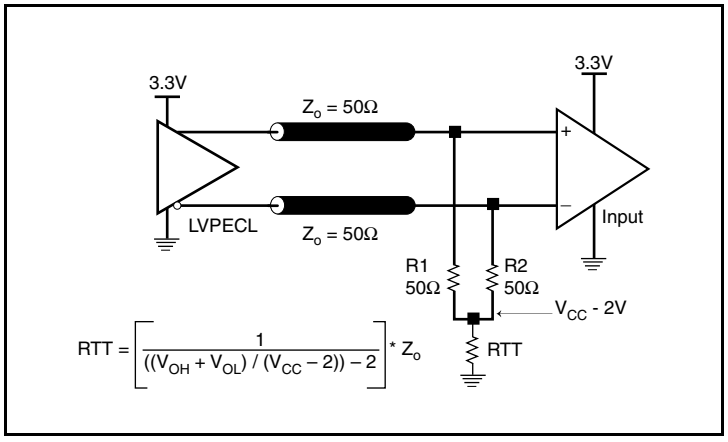


Figure 4A. 3.3V LVPECL Output Termination

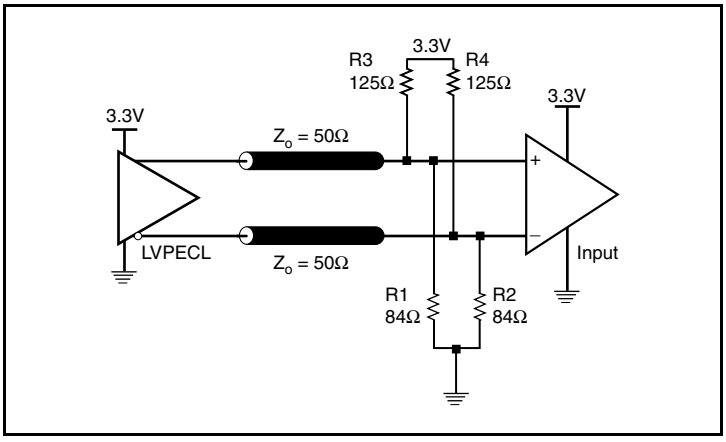


Figure 4B. 3.3V LVPECL Output Termination

Power Considerations

This section provides information on power dissipation and junction temperature for the ICS85304I-01.
Equations and example calculations are also provided.

1. Power Dissipation.

The total power dissipation for the ICS85304I-01 is the sum of the core power plus the power dissipated due to the load.
The following is the power dissipation for V_{CC} = 3.3V + 5% = 3.465V, which gives worst case results.

NOTE: Please refer to Section 3 for details on calculating power dissipated due to the load.

- Power $(core)_{MAX} = V_{CC\_MAX} * I_{EE\_MAX}$ = 3.465V * 55mA = **190.575mW**
- Power $(outputs)_{MAX}$ = **30mW/Loaded Output pair**
  If all outputs are loaded, the total power is 5 * 30mW = **150mW**

Total Power$_{\_MAX}$ (3.465V, with all outputs switching) = 190.575mW + 150mW = **340.575mW**

2. Junction Temperature.

Junction temperature, Tj, is the temperature at the junction of the bond wire and bond pad and directly affects the reliability of the device. The maximum recommended junction temperature for HiPerClockS devices is 125°C.

The equation for Tj is as follows: $Tj = \theta_{JA} * Pd\_total + T_A$

Tj = Junction Temperature

θ_{JA} = Junction-to-Ambient Thermal Resistance

Pd_total = Total Device Power Dissipation (example calculation is in section 1 above)

T_A = Ambient Temperature

In order to calculate junction temperature, the appropriate junction-to-ambient thermal resistance θ_{JA} must be used. Assuming a moderate air flow of 200 linear feet per minute and a multi-layer board, the appropriate value is 91.1°C/W per Table 6 below.

Therefore, Tj for an ambient temperature of 85°C with all outputs switching is:

85°C + 0.341W * 91.1°C/W = 116.06°C. This is below the limit of 125°C.

This calculation is only an example. Tj will obviously vary depending on the number of loaded outputs, supply voltage, air flow and the type of board (multi-layer).

Table 6. Thermal Resistance θ_{JA} for 20 Lead TSSOP, Forced Convection

θ_{JA} **by Velocity**			
Meters per Second	**0**	**1**	**2.5**
Multi-Layer PCB, JEDEC Standard Test Boards	91.1°C/W	86.7°C/W	84.6°C/W

3. Calculations and Equations.

The purpose of this section is to derive the power dissipated into the load.

LVPECL output driver circuit and termination are shown in *Figure 5.*

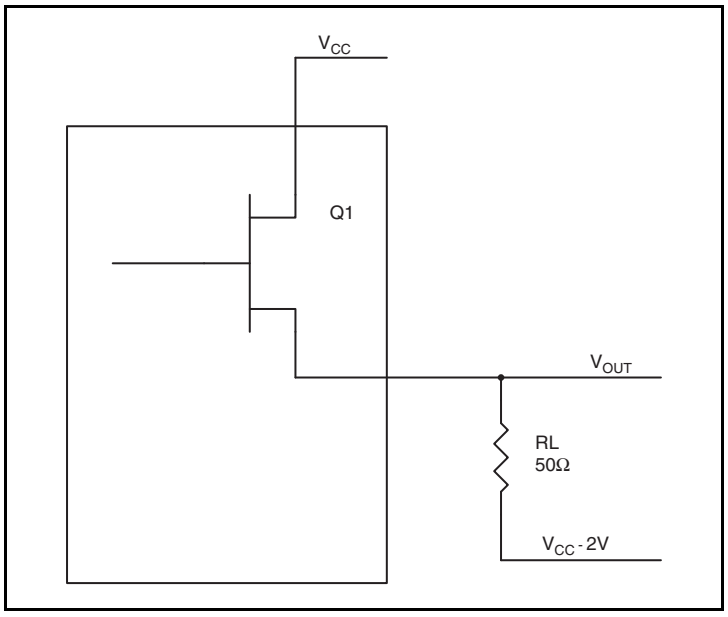


Figure 5. LVPECL Driver Circuit and Termination

To calculate power dissipation due to the load, use the following equations which assume a 50Ω load, and a termination voltage of V_{CC} – 2V.

- For logic high, $V_{OUT} = V_{OH\_MAX} =$ **V_{CC_MAX} – 0.9V**
  ($V_{CC\_MAX} – V_{OH\_MAX}$) = **0.9V**
- For logic low, $V_{OUT} = V_{OL\_MAX} =$ **V_{CO_MAX} – 1.7V**
  ($V_{CC\_MAX} – V_{OL\_MAX}$) = **1.7V**

Pd_H is power dissipation when the output drives high.

Pd_L is the power dissipation when the output drives low.

$Pd\_H = [(V_{OH\_MAX} – (V_{CC\_MAX} – 2V))/R_L] * (V_{CC\_MAX} – V_{OH\_MAX}) = [(2V - (V_{CC\_MAX} – V_{OH\_MAX}))/R_L] * (V_{CC\_MAX} – V_{OH\_MAX}) =$
[(2V - 0.9V)/50Ω] * 0.9V = **19.8mW**

$Pd\_L = [(V_{OL\_MAX} – (V_{CC\_MAX} – 2V))/R_L] * (V_{CC\_MAX} – V_{OL\_MAX}) = [(2V – (V_{CC\_MAX} – V_{OL\_MAX}))/R_{L]} * (V_{CC\_MAX} – V_{OL\_MAX}) =$
[(2V – 1.7V)/50Ω] * 1.7V = **10.2mW**

Total Power Dissipation per output pair = Pd_H + Pd_L = **30mW**

Reliability Information

Table 7. θ_{JA} vs. Air Flow Table for a 20 Lead TSSOP

θ_{JA} by Velocity			
Meters per Second	**0**	**1**	**2.5**
Multi-Layer PCB, JEDEC Standard Test Boards	91.1°C/W	86.7°C/W	84.6°C/W

Transistor Count

The transistor count for ICS85304I-01 is: 489

Package Outline and Package Dimensions

Package Outline - G Suffix for 20 Lead TSSOP

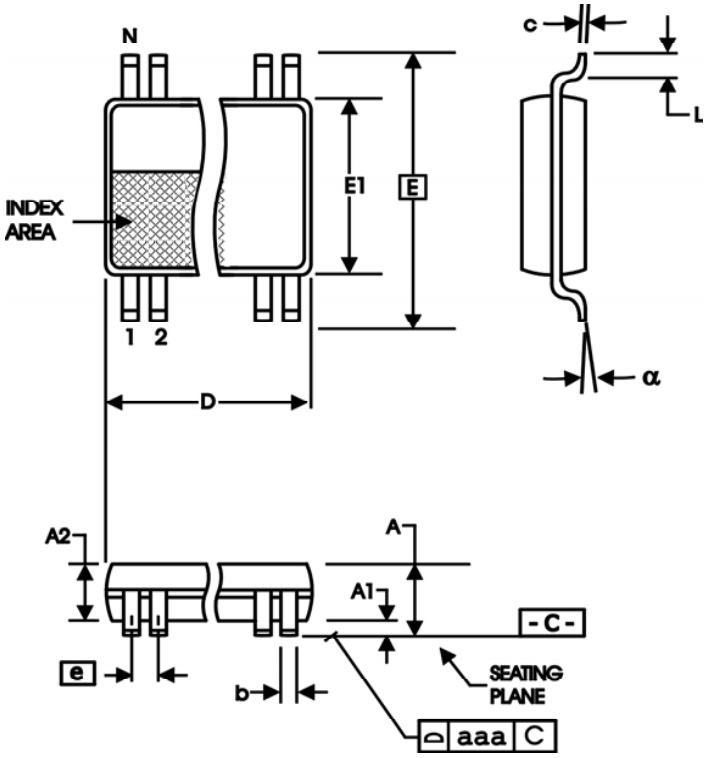


Table 8. Package Dimensions

All Dimensions in Millimeters		
Symbol	**Minimum**	**Maximum**
N	20	
A		1.20
A1	0.05	0.15
A2	0.80	1.05
b	0.19	0.30
c	0.09	0.20
D	6.40	6.60
E	6.40 Basic	
E1	4.30	4.50
e	0.65 Basic	
L	0.45	0.75
α	0°	8°
aaa		0.10

Reference Document: JEDEC Publication 95, MO-153

Ordering Information

Table 9. Ordering Information

Part/Order Number	Marking	Package	Shipping Packaging	Temperature
85304AGI-01LF	ICS85304AI01	“Lead-Free” 20 Lead TSSOP	Tube	-40°C to 85°C
85304AGI-01LFT	ICS85304AI01	“Lead-Free” 20 Lead TSSOP	Tape & Reel	-40°C to 85°C

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